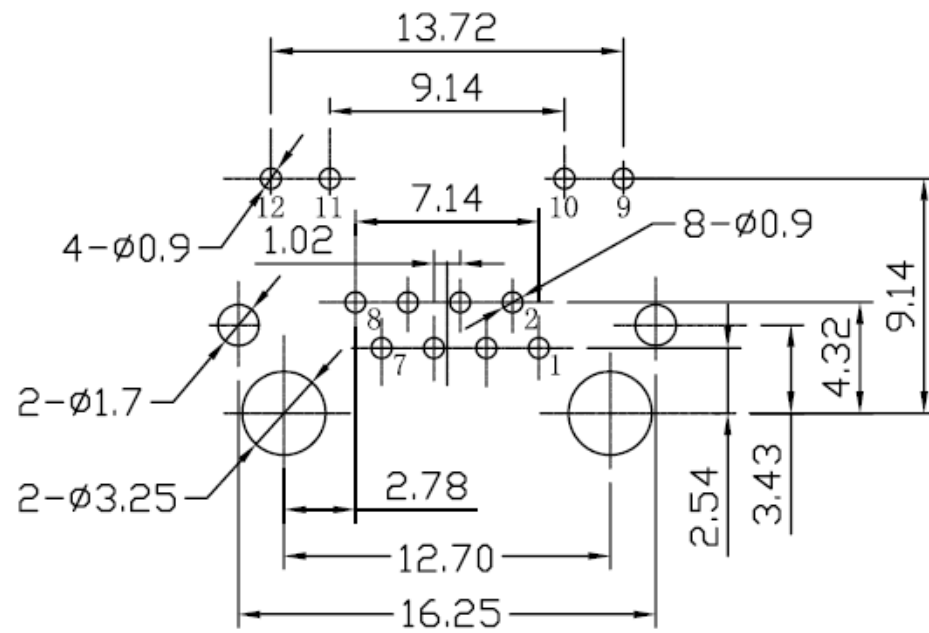
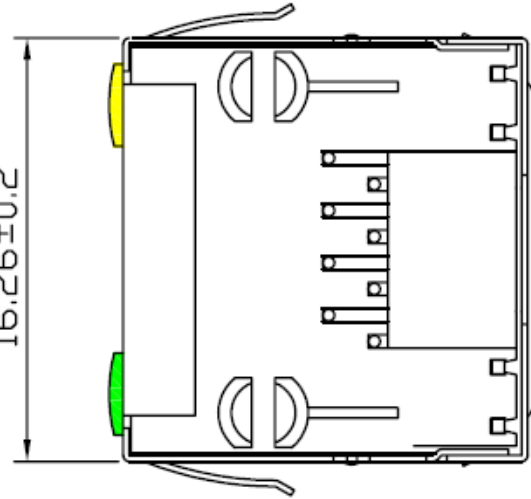


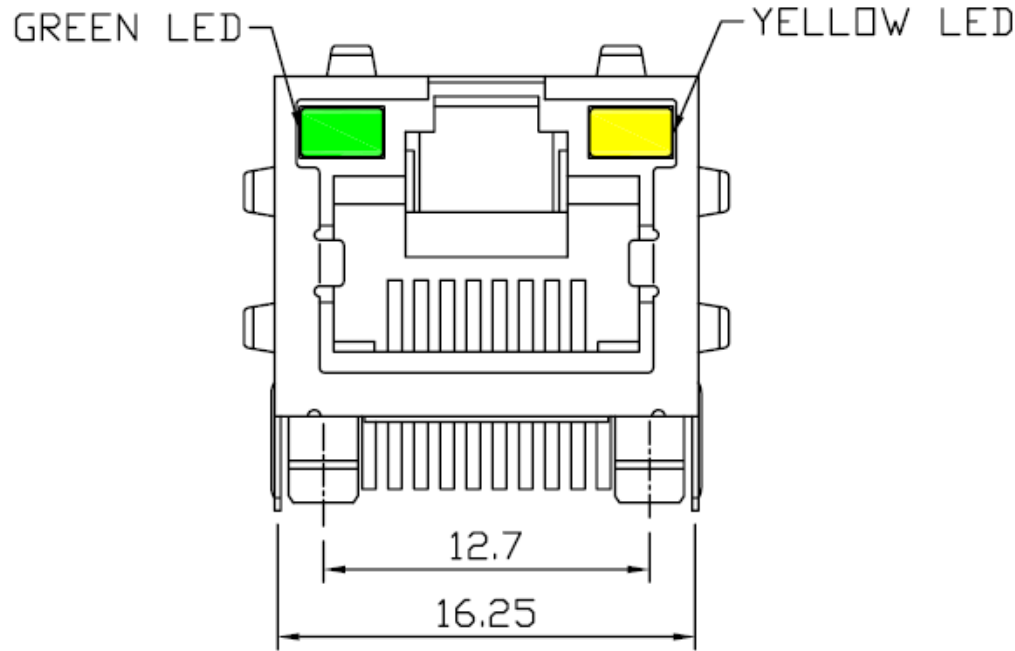
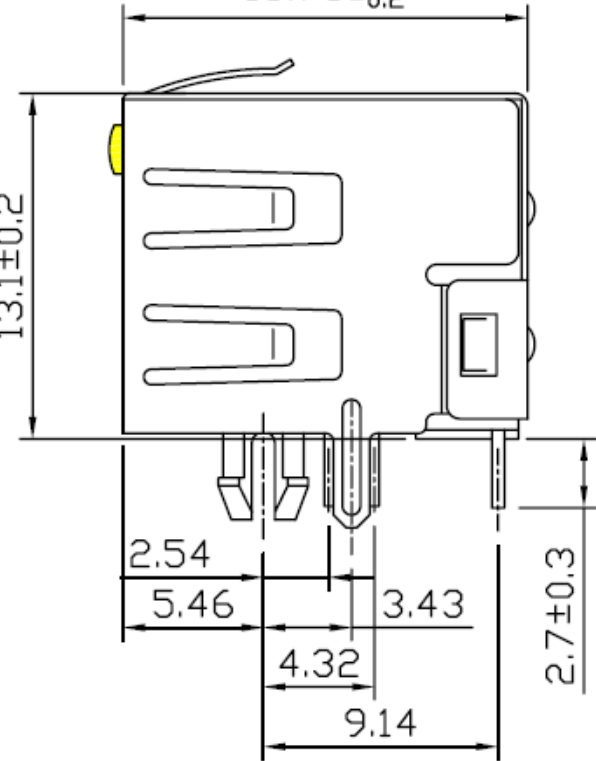
16.26±0.2



PC Board Layout (TOP VIEW)

13.1±0.2

15.75<sup>0</sup><sub>-0.2</sub>



NOTES:

PCB JACK Specification

1. Insulation Resistance: 500MΩ MIN @ 500 VDC
2. Withstanding Voltage: AC1000V 50Hz or 60Hz 1min.
3. Durability: 600 Mating Circles MIN.
4. Gold Plating:  
(Gold Flash; 1.5; 3; 6; 15; 30; 50)u" inch

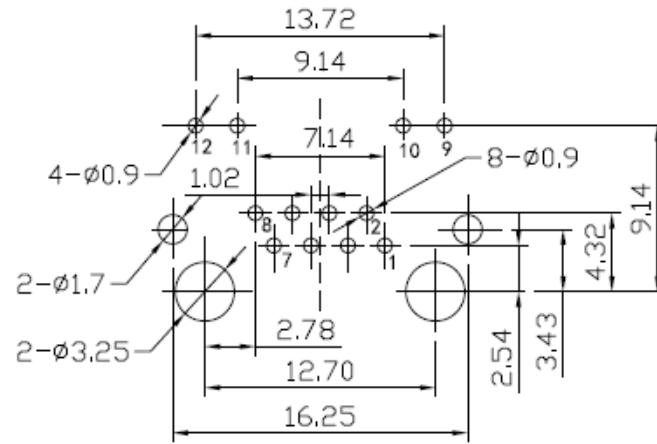
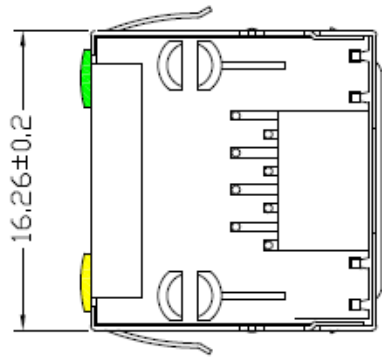
ENVIRONMENTAL

1. Storage Temperature: -40°C To +85°C
2. Operation Temperature: -40°C To +85°C
3. Wave Soldering Temperature:  
255°C ~ 265°C (5 ~ 10 Seconds)
4. RoHS Compliant.

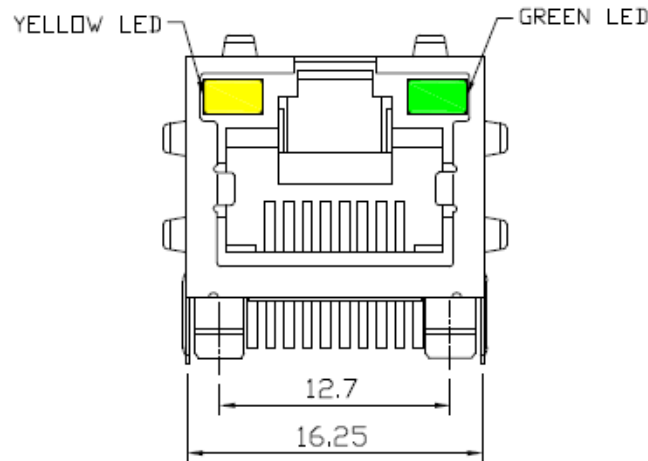
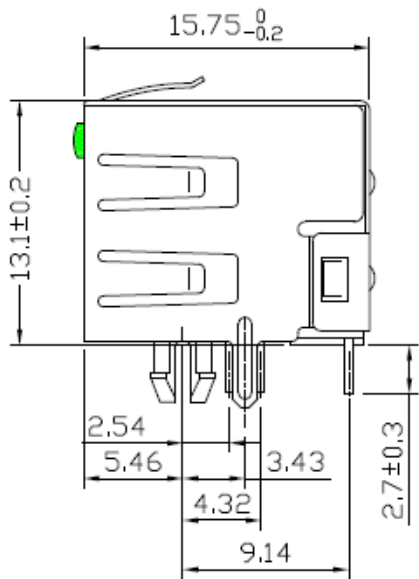
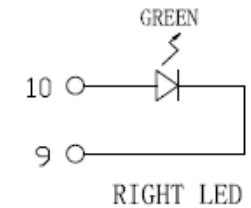
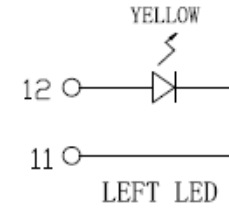


Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		17/09/2009	



SUGGESTED PCB LAYOUT  
(TOP VIEW)



PCB JACK Specification

1. Insulation Resistance: 500M Ω MIN @ 500 VDC
2. Withstanding Voltage: AC1000V 50Hz or 60Hz 1min.
3. Durability: 600 Mating Circles MIN.
4. Gold Plating: (Gold Flash; 1.5; 3; 6; 15; 30; 50  ) U" Inch
5. (1) Storage: -40°C to +85°C  
(2) Operation: -40°C to +85°C  
(3) Wave solder temperature: 230°C to 250°C, 5~10 Sec.

